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2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Freewheeling
- Snubber
- DC/DC converters
- Automotive application

MECHANICAL DATA

- Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.029g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	2	А	
V _{RRM}	200 - 1000	V	
I _{FSM}	50	А	
T _{J MAX}	150	°C	
Package	Thin SMA		
Configuration	Single die		



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2D ALH	RS2G ALH	RS2J Alh	RS2K ALH	RS2M ALH	UNIT
Marking code on the device			RS2DAH	RS2GAH	RS2JAH	RS2KAH	RS2MAH	
Repetitive peak reverse volta	ıge	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I _F			2			А
Surge peak forward current, t = 8.3ms		I			50			А
single half sine-wave superimposed on rated load	t = 1.0ms	I _{FSM}			140			А
Junction temperature		Τ _J			-55 to +150)		°C
Storage temperature		T _{STG}			-55 to +150)		°C



RS2DALH – RS2MALH

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	16	°C/W	
Junction-to-ambient thermal resistance	R _{eJA}	73	°C/W	
Junction-to-case thermal resistance	R _{eJC}	14	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
		$I_F = 1A, T_J = 25^{\circ}C$		0.93	-	V
	RS2DALH	$I_F = 2A, T_J = 25^{\circ}C$		1.01	1.30	V
	RS2GALH RS2JALH	$I_F = 1A, T_J = 125^{\circ}C$		0.78	-	V
Γ_{excused} is a set of $\Gamma_{\text{exc}}^{(1)}$		$I_F = 2A, T_J = 125^{\circ}C$	N	0.88	1.02	V
Forward voltage ⁽¹⁾		$I_F = 1A, T_J = 25^{\circ}C$	– V _F	0.98	-	V
	RS2KALH	$I_F = 2A, T_J = 25^{\circ}C$		1.06	1.30	V
	RS2MALH	$I_F = 1A, T_J = 125^{\circ}C$		0.83	-	V
		$I_F = 2A, T_J = 125^{\circ}C$		0.93	1.05	V
Reverse current @ rated V _R ⁽²⁾		$T_J = 25^{\circ}C$		-	1	μA
		T _J = 125°C	I _R	-	40	μA
	RS2DALH RS2GALH	I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A	t _{rr}	-	150	ns
Reverse recovery time	RS2JALH			-	250	ns
	RS2KALH RS2MALH			-	500	ns
Junction capacitance	RS2DALH RS2GALH RS2JALH	1MHz, V _B = 4.0V	CJ	11	-	pF
·	RS2KALH RS2MALH		-	10	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
RS2xALH	Thin SMA	14,000 / Tape & Reel	

Notes:

1. "x" defines voltage from 200V(RS2DALH) to 1000V(RS2MALH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

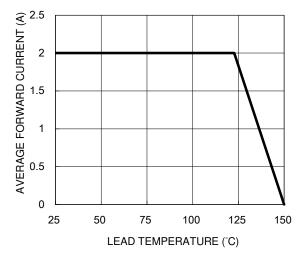


Fig.3 Typical Reverse Characteristics

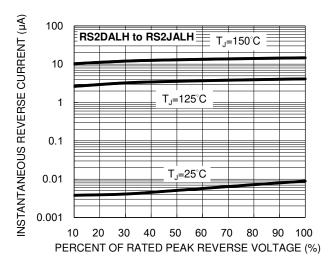
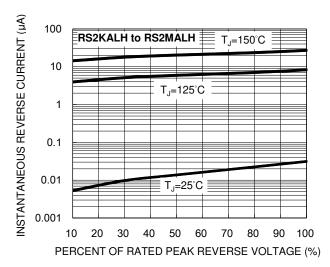


Fig.5 Typical Reverse Characteristics



100 (J) BOUTORO

Fig.2 Typical Junction Capacitance



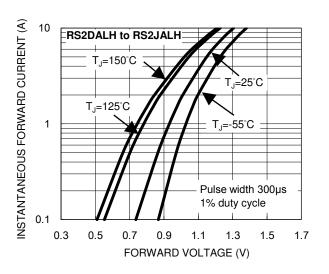
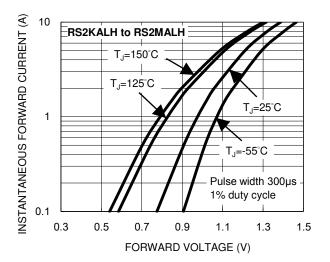


Fig.6 Typical Forward Characteristics



RS2DALH – RS2MALH

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CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

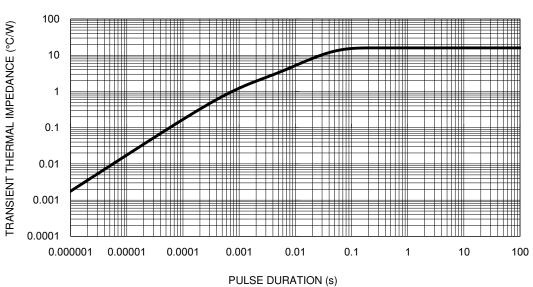


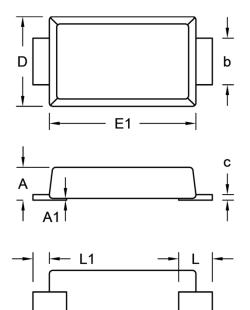
Fig.7 Typical Transient Thermal Impedance



RS2DALH – RS2MALH Taiwan Semiconductor

PACKAGE OUTLINE DIMENSIONS

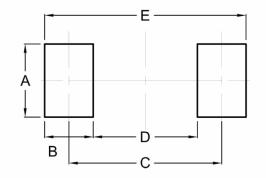




DIM.	Unit	(mm)	Unit (inch)		
	Min.	Max.	Min.	Max.	
A	0.90	1.00	0.035	0.039	
A1	0.00	0.10	0.000	0.004	
b	1.25	1.45	0.049	0.057	
с	0.10	0.22	0.004	0.009	
D	2.50	2.70	0.098	0.106	
E	5.05	5.35	0.199	0.211	
E1	4.15	4.35	0.163	0.171	
L	0.75	1.20	0.030	0.047	
L1	0.30	0.60	0.012	0.024	

SUGGESTED PAD LAYOUT

- E -



Symbol	Unit (mm)	Unit (inch)
А	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N	= Marking Code
YW	= Date Code
F	= Factory Code

Version: B2103



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